

PC357N Series

Mini-flat Package, General Purpose Photocoupler



■ Description

PC357N Series contains an IRED optically coupled to a phototransistor.

It is packaged in a 4-pin Mini-flat package. Input-output isolation voltage(rms) is 3.75kV. Collector-emitter voltage is 80V(*) and CTR is 50% to 600% at input current of 5mA.

■ Features

- 1. 4-pin Mini-flat package
- 2. Double transfer mold package (Ideal for Flow Soldering)
- 3. High collector-emitter voltage (V_{CEO}: 80V^(*))
- 4. Current transfer ratio (CTR) : MIN. 50% at I_F =5mA, V_{CF} =5V
- 5. Several CTR ranks available
- 6. High isolation voltage between input and output $(V_{iso(rms)}: 3.75kV)$
 - (*) Up to Date code "P9" (September 2002) V_{CEO} : 35V. From the production Date code "J5" (May 1997) to "P9" (September 2002), however the products were screened by $BV_{CEO} \ge 70V$.

■ Agency approvals/Compliance

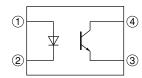
- Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. PC357)
- 2. Package resin: UL flammability grade (94V-0)

Applications

- 1. Hybrid substrates that require high density mounting
- 2. Programmable controllers



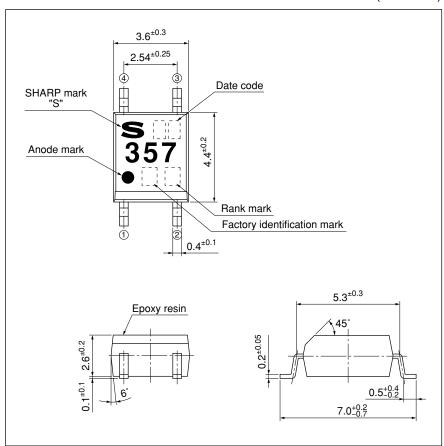
■ Internal Connection Diagram



- 1 Anode
- ② Cathode
- 3 Emitter
- 4 Collector

■ Outline Dimensions

(Unit:mm)



Product mass: approx. 0.1g



Date code (2 digit)

	1st o	digit		2nd digit		
	Year of p	roduction		Month of production		
A.D.	Mark	A.D	Mark	Month	Mark	
1990	A	2002	P	January	1	
1991	В	2003	R	February	2	
1992	С	2004	S	March	3	
1993	D	2005	T	April	4	
1994	Е	2006	U	May	5	
1995	F	2007	V	June	6	
1996	Н	2008	W	July	7	
1997	J	2009	X	August	8	
1998	K	2010	A	September	9	
1999	L	2011	В	October	0	
2000	M	2012	С	November	N	
2001	N	:	<u> </u>	December	D	

repeats in a 20 year cycle

Factory identification mark

Factory identification Mark	Country of origin
no mark	Iomon
	Japan
4	Indonesia
$\overline{\hspace{1cm}}$	Philippines
_	China

^{*} This factory marking is for identification purpose only.

Please contact the local SHARP sales representative to see
the actual status of the production

Rank mark

Refer to the Model Line-up table



■ Absolute Maximum Ratings

	■ Absolute Maximum Ratings $(T_a=25^{\circ}C)$							
	Parameter	Symbol	Rating	Unit				
	Forward current	I_F	50	mA				
Input	*1 Peak forward current	I_{FM}	1	A				
In	Reverse voltage	V_R	6	V				
	Power dissipation	P	70	mW				
	Collector-emitter voltage	V_{CEO}	*4 80	V				
Output	Emitter-collector voltage	V _{ECO}	6	V				
Out	Collector current	I_{C}	50	mA				
	Collector power dissipation	P_{C}	150	mW				
-	Total power dissipation	P _{tot}	170	mW				
(Operating temperature	Topr	-30 to +100	°C				
	Storage temperature	T_{stg}	-40 to +125	°C				
*2]	Isolation voltage	V _{iso (rms)}	3.75	kV				
*3 (Soldering temperature	T_{sol}	260	°C				

■ Electro-optical Characteristics

 $(T_a=25^{\circ}C)$

						(1_a-25)		
Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Forward voltage		V_F	$I_F=20mA$	-	1.2	1.4	V
Input	Reverse curre	nt	I_R	$V_R=4V$	_	_	10	μΑ
	Terminal capacitance		C_{t}	V=0, $f=1kHz$	_	30	250	pF
	Collector dark current		I_{CEO}	$V_{CE}=50V, I_{F}=0$	_	_	100	nA
Output	Collector-emitter breakdown voltage		BV_{CEO}	I_{C} =0.1mA, I_{F} =0	*5 80	-	-	V
	Emitter-collector breakdown voltage		BV _{ECO}	$I_{E}=10\mu A, I_{F}=0$	6	-	-	V
	Collector current		I_C	$I_F=5mA, V_{CE}=5V$	2.5	5	30	mA
	Collector-emitter saturation voltage		V _{CE (sat)}	$I_F=20\text{mA}, I_C=1\text{mA}$	_	0.1	0.2	V
Transfer charac- teristics	Isolation resistance		R_{ISO}	DC500V, 40 to 60%RH	5×10 ¹⁰	1×10 ¹¹	_	Ω
	Floating capacitance		C_{f}	V=0, f=1MHz	_	0.6	1.0	pF
		Rise time	t_r	W AW I A A B 1000	_	4	18	μs
	Response time	Fall time	t_{f}	$V_{CE}=2V$, $I_{C}=2mA$, $R_{L}=100\Omega$	_	3	18	μs

^{*5} From the production Date code "J5" (May 1997) to "P9" (September 2002), however the products were screened by BV_{CEO}≥70V.

^{*1} Pulse width≤100µs, Duty ratio : 0.001 *2 40 to 60%RH, AC for 1 minute, f=60Hz

^{*3} For 10s

^{*4} Up to Date code "P9" (September 2002) V_{CEO}:35V.



■ Model Line-up

Doolrage	Tap	oing	Rank mark	I _C [mA]	
Package	3 000pcs/reel 750pcs/re		Kank mark	$(I_F=5mA, V_{CE}=5V, T_a=25^{\circ}C)$	
	PC357N	PC357NT	with or without	2.5 to 30.0	
	PC357N1	PC357N1T	A	4.0 to 8.0	
	PC357N2	PC357N2T	В	6.5 to 13.0	
	PC357N3	PC357N3T	С	10.0 to 20.0	
Model No.	PC357N4	PC357N4T	D	15.0 to 30.0	
Model No.	PC357N5	PC357N5T	A or B	4.0 to 13.0	
	PC357N6	PC357N6T	B or C	6.5 to 20.0	
	PC357N7	PC357N7T	C or D	10.0 to 30.0	
	PC357N8	PC357N8T	A, B or C	4.0 to 20.0	
	PC357N9	PC357N9T	B, C or D	6.5 to 30.0	
	PC357N0	PC357N0T	A, B, C or D	4.0 to 30.0	

Please contact a local SHARP sales representative to inquire about production status and Lead-Free options.



Fig.1 Forward Current vs. Ambient Temperature

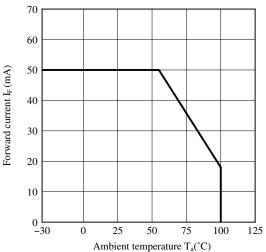


Fig.3 Collector Power Dissipation vs. Ambient Temperature

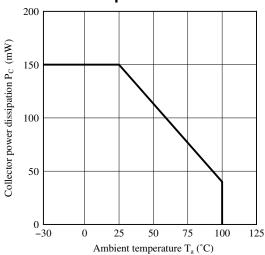


Fig.5 Peak Forward Current vs. Duty Ratio

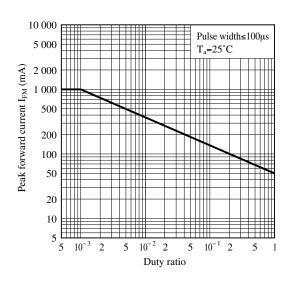


Fig.2 Diode Power Dissipation vs. Ambient Temperature

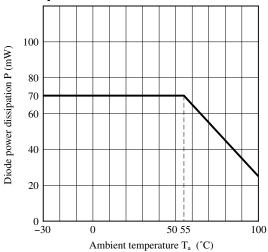


Fig.4 Total Power Dissipation vs. Ambient Temperature

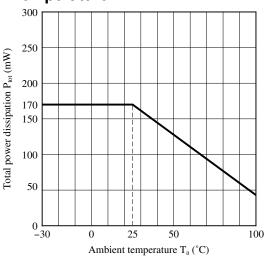


Fig.6 Forward Current vs. Forward Voltage

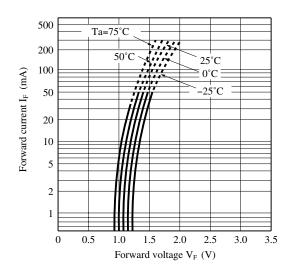




Fig.7 Current Transfer Ratio vs. Forward Current

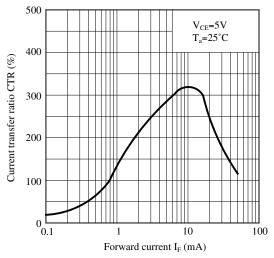


Fig.9 Relative Current Transfer Ratio vs. Ambient Temperature

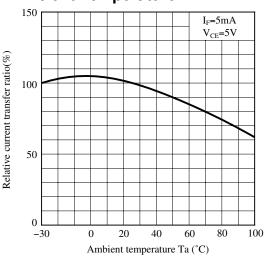


Fig.11 Collector Dark Current vs. Ambient Temperature

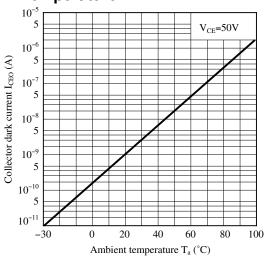


Fig.8 Collector Current vs. Collector-emitter Voltage

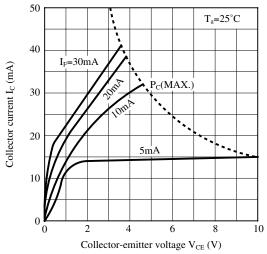


Fig.10 Collector - emitter Saturation Voltage vs. Ambient Temperature

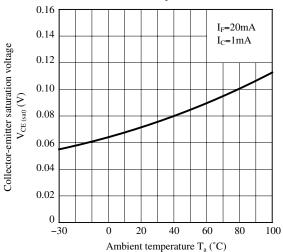


Fig.12 Response Time vs. Load Resistance

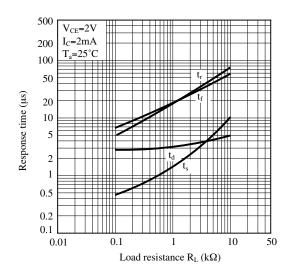
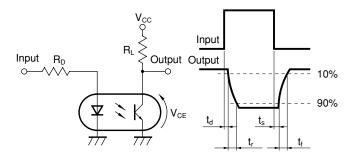


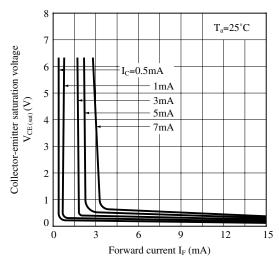


Fig.13 Test Circuit for Response Time



Please refer to the conditions in Fig.12

Fig.14 Collector-emitter Saturation Voltage vs. Forward Current



Remarks: Please be aware that all data in the graph are just for reference and not for guarantee.



■ Design Considerations

Design guide

While operating at I_F<1.0mA, CTR variation may increase.

Please make design considering this fact.

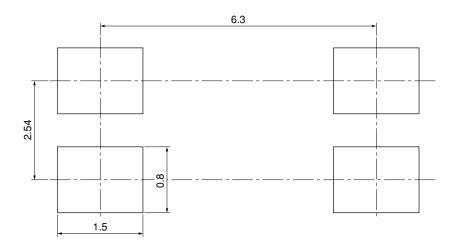
This product is not designed against irradiation and incorporates non-coherent IRED.

Degradation

In general, the emission of the IRED used in photocouplers will degrade over time.

In the case of long term operation, please take the general IRED degradation (50% degradation over 5years) into the design consideration.

Recommended Foot Print (reference)



(Unit: mm)

[☆] For additional design assistance, please review our corresponding Optoelectronic Application Notes.



■ Manufacturing Guidelines

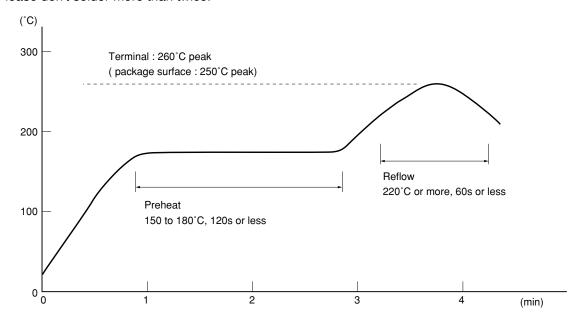
Soldering Method

Reflow Soldering:

Reflow soldering should follow the temperature profile shown below.

Soldering should not exceed the curve of temperature profile and time.

Please don't solder more than twice.



Flow Soldering:

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 260°C and within 10s.

Preheating is within the bounds of 100 to 150°C and 30 to 80s.

Please don't solder more than twice.

Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C.

Please don't solder more than twice.

Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



Cleaning instructions

Solvent cleaning:

Solvent temperature should be 45°C or below Immersion time should be 3minutes or less

Ultrasonic cleaning:

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

Recommended solvent materials:

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this device.

Regulation substances: CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

Sheet No.: D2-A00101EN



■ Package specification

● Tape and Reel package

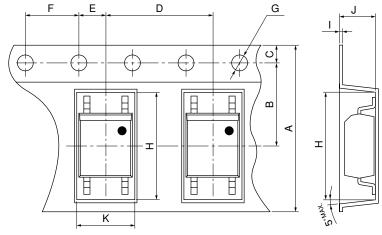
1. 3 000pcs/reel Package materials

Carrier tape: A-PET (with anti-static material)

Cover tape: PET (three layer system)

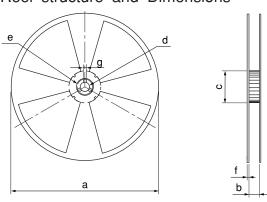
Reel: PS

Carrier tape structure and Dimensions



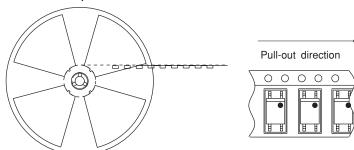
Dimension	(L	Jnit: mm)				
A	В	C	D	Е	F	G
12.0 ^{±0.3}	5.5 ^{±0.1}	1.75 ^{±0.1}	8.0 ^{±0.1}	2.0 ^{±0.1}	4.0 ^{±0.1}	φ1.5 - 8.1
Н	I	J	K			
7.4 ^{±0.1}	0.3 ^{±0.05}	3.1 ^{±0.1}	4.0 ^{±0.1}			

Reel structure and Dimensions



	Dimensio	ns List	(Unit: mm)			
	a	b	c	d		
	370 13.5±1.5		80 ^{±1.0}	13 ^{±0.5}		
ľ	e	f	g			
	21 ^{±1.0}	2.0±0.5	2.0 ^{±0.5}			

Direction of product insertion



[Packing: 3 000pcs/reel]



2. 750pcs/reel

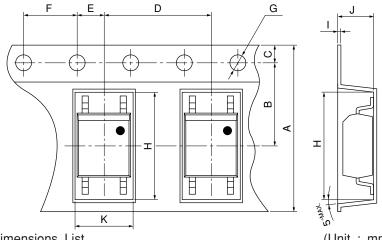
Package materials

Carrier tape: A-PET (with anti-static material)

Cover tape: PET (three layer system)

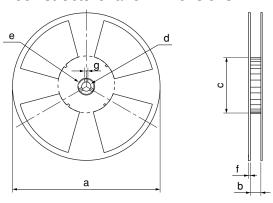
Reel: PS

Carrier tape structure and Dimensions



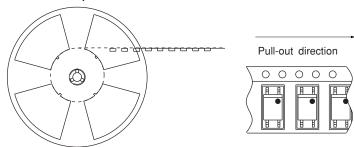
Dimension	ns list				(L	<u> init : mm)</u>
A	В	C	D	Е	F	G
12.0 ^{±0.3}	5.5 ^{±0.1}	1.75 ^{±0.1}	8.0 ^{±0.1}	2.0 ^{±0.1}	4.0 ^{±0.1}	φ1.5 + 8.1
Н	I	J	K			
$7.4^{\pm0.1}$	0.3 ^{±0.05}	3.1 ^{±0.1}	4.0 ^{±0.1}			

Reel structure and Dimensions



Dimensio	ns List	(Unit: mm)		
a	b	с	d	
180	13.5 ^{±1.5}	80±1.0	13±0.5	
e	f	g		
21 ^{±1.0}	2.0±0.5	2.0±0.5		

Direction of product insertion



[Packing: 750pcs/reel]



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